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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/924,787	08/08/2001	Sung-Bae Park	SAM-0234	2796	
75	90 05/22/2002				
Steven M. Mills			EXAMINER		
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Boston, MA 02			ART UNIT	PAPER NUMBER	
200.000,			2822		
			DATE MAILED: 05/22/2002		

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application	Application No.		
			09/924,787		
	Office Action Summary	Examiner		Art Unit	
		Monica Lew	<i>i</i> is	2822	address
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Status					
1)🛛	Responsive to communication(s)	OLIVE This action is	non-final.		
2a)□	This action is FINAL.		Lier formal matt	ers, prosecution as t	to the merits is
3)	This action is FINAL . Since this application is in condit closed in accordance with the process of the conditions of the conditions.	tion for allowance excep actice under Ex parte Q	uayle, 1935 C.E). 11, 453 O.G. 213.	
Dispositi	ion of Claims				
4)⊠	Claim(s) 1-6 is/are pending in the	e/are withdrawn from co	insideration.		
	4a) Of the above claim(s)i	istaic withdrawn hom of			
	Claim(s) is/are allowed.				
6)🖾	Claim(s) <u>1-6</u> is/are rejected.				
7)	Claim(s) is/are objected to	O.	requirement.		
8)] Claim(s) are subject to re	estriction and/or election	, oquit official		
Applica	ition Papers	w the Evaminer			
9)[The specification is objected to b The drawing(s) filed on <u>08 Augus</u>	-1 0001 ic/ore: 311X1 300cl	pted or b) obje	cted to by the Examir	ner.
10)⊠	The drawing(s) filed on <u>08 Augus</u> Applicant may not request that an	v objection to the drawing	s) be held in abe	yance. See 37 CFR 1.	85(a).
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11)[The proposed drawing correction	are required in renly to this	Office action.		
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Priorit	y under 35 U.S.C. §§ 119 and 120	U	under 35 U.S.C	;, § 119(a)-(d) or (f).	
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	Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing R Information Disclosure Statement(s) (PTC	Review (PTO-948))-1449) Paper No(s)	5) Notice 6) Othe	e of Informal Patent Appli	
3) [_]	Information Disclosure Otacine (6) (1.1)				Part of Paper No. 5

DETAILED ACTION

1. This office action is in response to the election filed April 22, 2002.

Claim Objections

2. Claims 2 and 3 are objected to because of the following informalities: a) "of at least one of metal and polysilicon" appears to be a grammatical error (See Claim 2); and b) "of one of a metal layer, a tungsten layer, a silicon epitaxial layer" and "of at least two of a metal layer, a tungsten layer and a silicon epitaxial layer" appear to be a grammatical errors (See Claim 3). Appropriate correction is required.

Claim Rejections - 35 USC § 112

- 3. The following is a quotation of the second paragraph of 35 U.S.C. 112:

 The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.
- 4. Claims 1-6 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention. It is not clear what is meant by the following:

 a) "forming a trench perforating an isolation region, the body, and the buried oxide layer" (See Claim 1). Claims 2-6 depend directly or indirectly from a rejected claim and are, therefore, also rejected under 35 U.S.C. 112, second paragraph for the reasons set above.

Claim Rejections - 35 USC § 103

- 5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

6. Claims 1 and 4, as far as understood, are rejected under 35 U.S.C. 103(a) as obvious over Applicant's Prior Art Drawings in view of Rutten et al.(U.S. Patent No. 5,889,293).

In regards to claim 1, Applicant's Prior Art Drawings disclose the following:

- a) a semiconductor substrate (20) (See Figure 2);
- b) a buried oxide layer (21) formed on the semiconductor substrate (See Figure 2);
- c) a body (14, 15) on the buried oxide layer, the body being an active region of a transistor (See Figure 2);
 - d) a gate oxide layer (18) formed on a body (See Figure 2);
 - e) a gate (16) formed on the gate oxide layer (See Figure 2); and
 - f) a body contact (12) supplying power to the body (See Figure 2).

In regards to claim 1, Applicant's Prior Art Drawings fail to disclose the following:

a) a trench perforating an isolation region, the body, and the buried oxide layer and filling the trench with a conductive material so that the body is electrically connected to the semiconductor substrate.

However, Rutten et al. ("Rutten") discloses a trench, which is filled with conductive material, that perforates various layers (See Column 7 Lines 35-53). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Applicant's Prior Art Drawings to include a trench, which is filled with conductive material, that perforates various layers as disclosed in Rutten because it aids in providing an electrical interconnection among the devices.

In regards to claim 4, Applicant's Prior Art Drawings disclose the following:

- a) a region into which predetermined impurity ions are implanted and generated on the semiconductor substrate in contact with the lower portion of the body contact so that an ohmic contact (110) is formed between the body contact and the semiconductor substrate (See Figure 3).
- 7. Claim 2, as far as understood, is rejected under 35 U.S.C. 103(a) as obvious over Applicant's Prior Art Drawings in view of Rutten et al.(U.S. Patent No. 5,889,293) and Adan et al. (U.S. Patent No. 5,841,170).

In regards to claim 2, Applicant's Prior Art Drawings fail to disclose the following:

a) gate is formed of at least one of metal and polysilicon.

However, Adan et al. ("Adan") discloses a gate that is composed of metal or polysilicon (See Column 10 Lines 9-11). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Applicant's Prior Art Drawings to include a gate composed of a metal or polysilicon as disclosed in Adan because they can withstand high temperature processing without degradation.

8. Claim 3, as far as understood, is rejected under 35 U.S.C. 103(a) as obvious over Applicant's Prior Art Drawings in view of Rutten et al.(U.S. Patent No. 5,889,293) and Hashimoto et al. (U.S. Patent No. 5,475,257).

In regards to claim 3, Applicant's Prior Art Drawings fail to disclose the following:

a) the conductive material formed of one of a metal layer, a tungsten layer, a silicon epitaxial layer, and a combination layer of at least two of a metal layer, a tungsten layer and a silicon epitaxial layer.

However, Hashimoto et al. ("Hashimoto") discloses layers of metal, tungsten and silicon epitaxial (See Column 3 Lines 18-34). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Applicant's Prior Art Drawings to include layers of metal, tungsten and silicon epitaxial as disclosed in Hashimoto because they aid in increasing the speed of the device.

9. Claim 5, as far as understood, is rejected under 35 U.S.C. 103(a) as obvious over Applicant's Prior Art Drawings in view of Rutten et al.(U.S. Patent No. 5,889,293) and Lynch et al. (U.S. Patent No. 4,646,123).

In regards to claim 5, Applicant's Prior Art Drawings fail to disclose the following:

a) the trench narrows as the trench deepens.

However, Lynch et al. ("Lynch") discloses a trench that narrows as it deepens (See Figure 3). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Applicant's Prior Art Drawings to include a trench that narrows as it deepens as disclosed in Lynch because it aids in keeping voids from forming.

10. Claim 6, as far as understood, is rejected under 35 U.S.C. 103(a) as obvious over Applicant's Prior Art Drawings in view of Rutten et al.(U.S. Patent No. 5,889,293) and Lynch et al. (U.S. Patent No. 4,646,123) and Abiko et al. (U.S. Patent No. 6,051,472).

In regards to claim 6, Applicant's Prior Art Drawings fail to disclose the following:

a) the trench narrows in a stepwise manner as the trench deepens.

However, Abiko et al. ("Akibo") discloses a trench that narrows in a stepwise manner (See Figure 17). It would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the semiconductor device of Applicant's Prior Art Drawings to include a trench that narrows in a step wise manner as disclosed in Abiko because it aids in keeping voids from forming.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Monica Lewis whose telephone number is 703-305-3743. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead, Jr. can be reached on 703-308-4940. The fax phone number for the organization where this application or proceeding is assigned is 703-308-7722 for regular and after final communications. Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

ML

May 16, 2002

SUPERMISORY PATENT S800

CARL WHITEHEAD, JR